

Design verification as per IEC/EN 61439

Technical data for design verification			
Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P _V	CO	77
Starting enclosure for wall mounting	P _V	CO	91
Middle enclosure for wall mounting	P _V	CO	78
Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P _V	CO	155
Starting enclosure for wall mounting	P _V	CO	183
Middle enclosure for wall mounting	P _V	CO	156
IEC/EN 61439 design verification			
10.2 Strength of materials and parts			
10.2.2 Corrosion resistance			Meets the product standard's requirements.
10.2.3.1 Verification of thermal stability of enclosures			Meets the product standard's requirements.
10.2.3.2 Verification of resistance of insulating materials to normal heat			Meets the product standard's requirements.
10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects			Meets the product standard's requirements.
10.2.4 Resistance to ultra-violet (UV) radiation			Not relevant to indoor installations.
10.2.5 Lifting			Does not apply to enclosures without lifting aids.
10.2.6 Mechanical impact			IK08
10.2.7 Inscriptions			Meets the product standard's requirements.
10.3 Degree of protection of ASSEMBLIES			IP30
10.4 Clearances and creepage distances			Is the panel builder's responsibility.
10.5 Protection against electric shock			< 0.1 Ω; meets the product standard's requirements.
10.6 Incorporation of switching devices and components			Is the panel builder's responsibility.
10.7 Internal electrical circuits and connections			Is the panel builder's responsibility.
10.8 Connections for external conductors			Is the panel builder's responsibility.
10.9 Insulation properties			
10.9.2 Power-frequency electric strength			U _i = 400 V AC
10.9.3 Impulse withstand voltage			2.5 kV
10.9.4 Testing of enclosures made of insulating material			Does not apply to metal enclosures.
10.10 Temperature rise			The panel builder is responsible for the temperature rise calculation. Eaton will provide heat dissipation data for the devices.
10.11 Short-circuit rating			Is the panel builder's responsibility.
10.12 Electromagnetic compatibility			Is the panel builder's responsibility.
10.13 Mechanical function			Meets the product standard's requirements.